

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC9271xxxxQR-G

Typical Mass: 80 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	2.378	Silicon	29700	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	23.135	Copper	289200	7440-50-8
	0.159	Silver	2000	7440-22-4
Die attach	0.761	Silver	9500	7440-22-4
	0.087	Epoxy	1100	—
Bonding wire	0.255	Gold	3200	7440-57-5
Resin	46.023	Silica	575300	60676-86-0
	4.184	Epoxy resin	52300	—
	1.674	Phenol resin	20900	—
Plating	1.344	Tin	16800	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."